Customer Information Notification

202610020I : BGA Substrate Core Conversion In NXP-ATKL and NXP-ATTJ Assembly Sites

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 03, 2026 **Effective Date:** Dec 03, 2026

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Notification Overview

Description

NXP Semiconductors announces the required substrate core conversion for the BGA package devices assembled in NXP-ATKL, Kuala Lumpur, Malaysia and NXP-ATTJ, Tianjin, China, associated with this notification.

Please refer to the attached communication package on new substrate core and qualification results.
New substrate core has been qualified adhering to NXP specifications.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-09

NXP estimates we will not be able to manufacture devices with current material beyond 30 November 2026.
Implementation of new substrate core is required on the CIN effective date, in order to ensure uninterrupted product supply.

Reason

To mitigate the impact of substrate core material shortage, and ensure ongoing customer supply, a new substrate core material has been qualified.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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